

485 Series Fuse

Rohs HF 🕀 🗣



Agency Approvals		
Agency	Agency File Number	Ampere Rating
A L	E10480	500mA - 3.15A
(Sft)	LR29862	500mA - 3.15A

Electrical Characteristics for Series

% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	60 seconds, Maximum

Description

The 485 Nano² Fuse Series is a small, fast acting, surface mount ceramic fuse rated at a remarkable 600VDC at its small size and with 100A breaking capacity. It is primarily designed for circuit protection in high energy applications. This product is fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.

Features

- Fast Acting / Surface mount high fuse for high voltage (up to 600VDC) applications.
- Fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.
- Relatively high breaking capacity at 100A.
- RoHS compliant / Halogen Free
- Rating 0.5 3.15 Amperes.

Applications

- PC server and Telecom systems
- LCD TV inverter boards DC input protection
- Uninterruptible Power Supply (UPS) / 3-Phase Power Supplies
- 380VDC server / lighting in data center

Electrical Specifications by Item

Ampere Rating Amp Code (A)	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I²t (A²sec)	Agency Approvals		
					PN °	()	
0.50	.500	600∨ 100 100,	100A @ 250V AC 100A @ 600V DC	0.807	0.0354	Х	Х
1.00	001.			0.264	0.3044	Х	Х
1.50	01.5			0.123	0.3917	Х	Х
2.00	002.			0.0744	0.8962	Х	Х
2.50	02.5			0.0583	1.4921	Х	Х
3.15	3.15			0.0395	3.304	Х	Х

Notes:

1. Cold resistance measured at less than 10% of rated current at 23°C.

2. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved.

3. I²t values stated for 8 msec opening time.



Surface Mount Fuses

Nano^{2®} > 600VDC > Fast-Acting 485 Series

Temperature Rerating Curve





Soldering Parameters - Reflow Soldering

Reflow Condition		Pb – Free Assembly	
	- Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 ses	
Average Ramp-up Rate (LiquidusTemp (T _L) to peak)		5°C/second max.	
T _{S(max)} to T _L - Ramp-up Rate		5°C/second max.	
Reflow	-Temperature (T_L) (Liquidus)	217°C	
	- Temperature (t _L)	60 – 150 seconds	
PeakTemperature (T _P)		260 ^{+0/-5} °C	
Time within 5°C of actual peak Temperature (t _p)		20 – 40 seconds	
Ramp-down Rate		5°C/second max.	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	



Product Characteristics

Material	Body: Ceramic Cap: Silver Plated Brass
Product Marking	Body: Brand Logo, Current Rating
Operating Temperature	-55°C to 125°C with proper derating
Moisture Sensitivity Level	Level 1 J-STD-020C
Solderability	MIL-STD-202, Method 208
Insulation Resistance (after Opening)	MIL-STD-202, Method 302, Test Condition A (10,000 ohms, Minimum)

Thermal Shock	MIL-STD-202, Method 107, Test Condition B, 5 cycles, -65°C to 125°C, 15 minutes @ each extreme
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I: Deenergized. 100G's peak amplitude, sawtooth wave 6ms duration, 3 cycles XYZ+xyz = 18 shocks
Vibratio	MIL-STD-202, Method 201: 0.03" amplitude, 10-55 Hz in 1 min. 2 hrs. each XYZ=6hrs
Moisture Resistance	MIL-STD-202F, Method 106, 10 cycles
Salt Spray	MIL-STD-202, Method 101, Test Condition B (48hrs)
Resistance to Soldering Heat	MIL-STD-202, Method 210, Test Condition B (10 sec at 260°C)

Part Numbering System



1500

DR

Dimensions

1

12.1 (.475″)



EIA-RS 481-1, (IEC 286, Part 3

Recommended Pad Layout

24mm Tape and Reel

